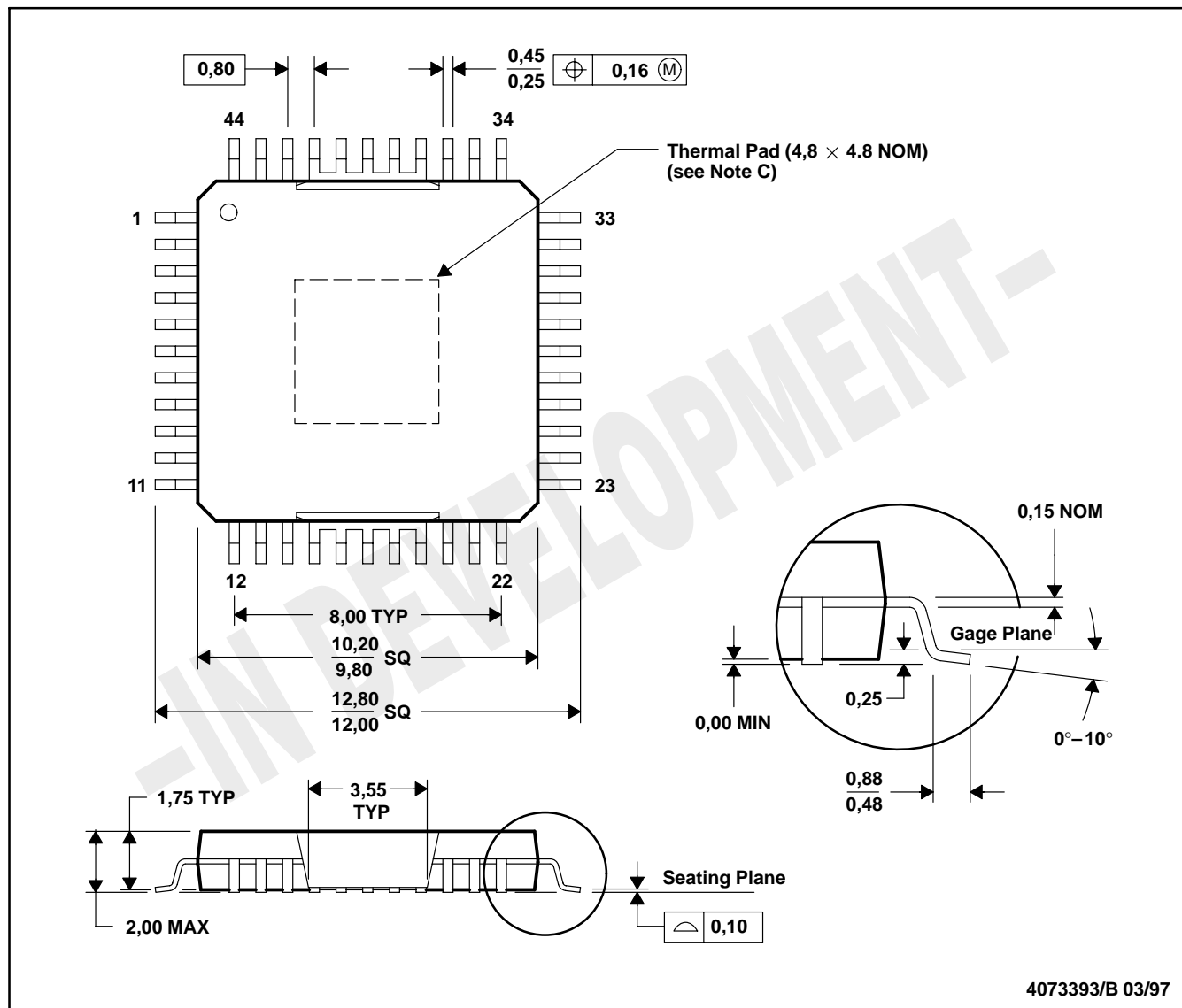


FRP (S-PQFP-G44)

PowerPAD™ PLASTIC QUAD FLATPACK



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. The package thermal performance may be enhanced by bonding the thermal pad to an external thermal plane. This solderable pad is electrically and thermally connected to the backside of the die and leads 15, 16, 17, 18, 19, 37, 38, 39, 40, and 41.

PowerPAD is a trademark of Texas Instruments Incorporated.

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